



# Alexander Birich



## Early Stage Gold Recovery from Printed Circuit Boards via Thiosulfate Leaching

# **Early Stage Gold Recovery from Printed Circuit Boards via Thiosulfate Leaching**

From the Faculty of Georesources and Materials Engineering of the  
RWTH Aachen University

Submitted by

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in respect of the academic degree of

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Approved thesis

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“The two most powerful warriors are patience and time.”

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„Die zwei mächtigsten Krieger sind Geduld und Zeit.“

Leo N. Tolstoi

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